

Performance Specification

Madal	Mar	V max	I _{max}	I hold	I _{trip}	Pd	Maximum Time To Trip		Resistance	
Model	king			@25°C	@25°C	Тур.	Current	Time	R i min	R1max
		(V dc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)
K1206L075/16AR	R7	16.0	35	0.75	1.50	0.6	8.00	0.20	0.090	0.500

V max = Maximum operating voltage device can withstand without damage at rated current (Imax).

I max = Maximum fault current device can withstand without damage at rated voltage (V max).

I hold = Hold Current. Maximum current device will not trip in 25°C still air.

I trip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Ri min/max = Minimum/Maximum device resistance prior to tripping at 25°C.

R1max = Maximum device resistance is measured one hour post reflow.

CAUTION: Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H., 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +8	5 °C	

Maximum surface temperature of the device in the tripped state is 125 °C

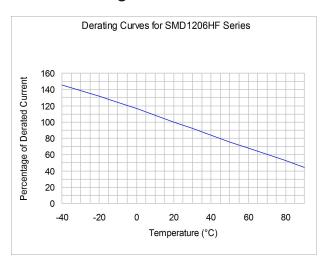
Thermal Derading Chart

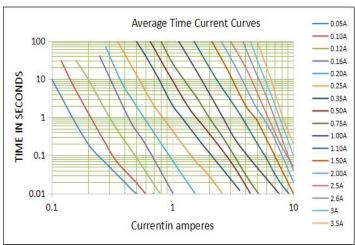
Recommended Hold Current(A) at Ambient Temperature(°C)

Model	Ambient Operation Temperature								
Wodei	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
K1206L075/16AR	1.14	1.01	0.88	0.75	0.65	0.59	0.54	0.49	0.41

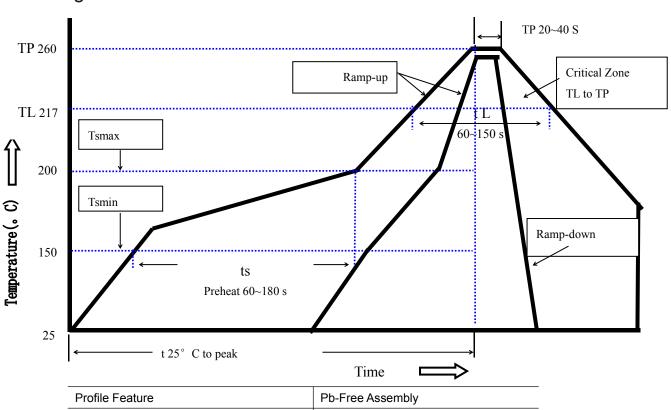
Thermal Derating Curve

Average Time-Current Curve





Soldering Parameters



Profile Feature	Pb-Free Assembly			
Average Ramp-Up Rate(Ts max to T p)	3℃/second mac.			
Preheat				
-Temperature Min(Ts min)	150℃			
-Temperature Max(Ts max)	200℃			
-Time(Ts min to Ts max)	60~180 seconds			
Time maintained above:				
-Temperature(TL)	217℃			
-Time(tL)	60~150 seconds			
Peak Temperature(Tp)	260℃			
Ramp-Down Rate	6℃/second max.			
Time 25℃ to Peak Temperature	8 minutes max			
Storage Condition	0℃~35℃,30%~60%RH			

Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free

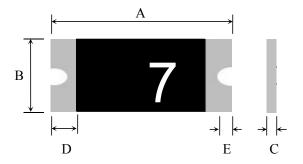
Recommended maximum paste thickness is 0.25mm

Devices can be cleaned using standard industry methods and solvents.

Note 1:All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Physical Dimensions(mm.)



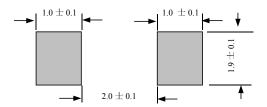
Model	Α		В		С		D	E
Woder	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
K1206L075/16AR	3.00	3.60	1.50	1.90	0.50	1.00	0.15	0.10

Termination Pad Characteristics

Terminal pad materials: Tin-plated Nickel-Copper

Terminal pad solder ability: Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

Recommended Pad Layout (mm.)



Packaging Quantity

Part Number	Quantity			
K1206L075/16AR	3500 pcs/reel			

Tape & reel packaging per EIA481-1

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